

FEATURES

Low profile package

I Ideal for automated placement

I 400 Watt peak pulse power capability with a $10/1000\mu s$ waveform

For surface mounted applications to optimize board space

| Excellent clamping capability

Very fast response time

Low incremental surge resistance

| Meet AEC-Q101 Requirements







Schematic Symbol

APPLICATIONS

Dowor	cunn	J.	protection
Power	Supp	υV	protection

Automotive application

Industrial application

Power management

APPROVALS

	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS ($T_A = 25$ °C)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation on T _A =25°C	P _{PPM}	400	W
Peak Forward Surge Current	I _{FSM}	40	А
Peak Pulse Current on 10/1000 us waveform	I _{PPM}	see Table 1	А

THERMAL CONSIDERATIONS

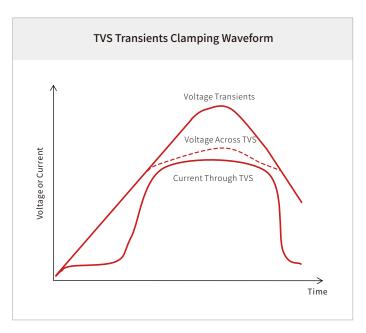
Parameter	Symbol	Value	Unit
Operating junction Temperature	T_{J}	-55 to +150	°C
Storage Temperature Range	T _s	-55 to +150	°C
Junction to Ambient on Printed circuit	$R_{\theta JA}$	150	°C/W

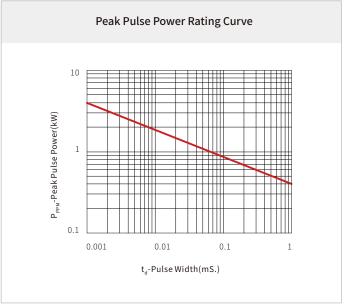


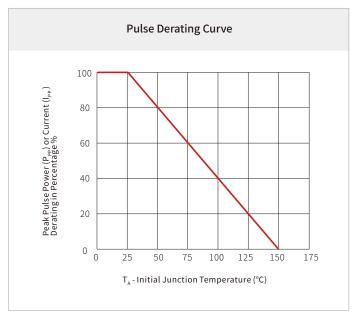
ELECTRICAL CHARACTERISTICS (T_A=25°C)

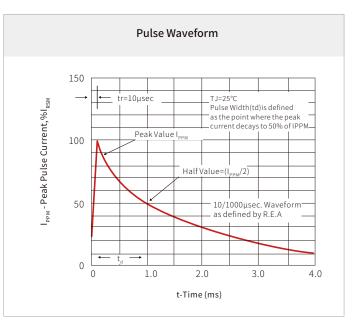
Part Number	Device Marking Code	Reverse Stand-off Voltage	Breakdown Voltage Min.@I _T	Breakdown Voltage Max.@I _T	Test Current	Maximum Clamping Voltage @I _{PP}	Peak Pulse Current	Reverse Leakage @V _{RWM}
		V _{RWM} (V)	V _{BR} (V)	V _{BR} (V)	I _⊤ (mA)	V _c (V)	I _{PP} (A)	I _R (uA)
TPSMAF18A	BTA	18.0	20.0	22.1	1.0	29.2	13.7	1.0

CHARACTERISTIC CURVES

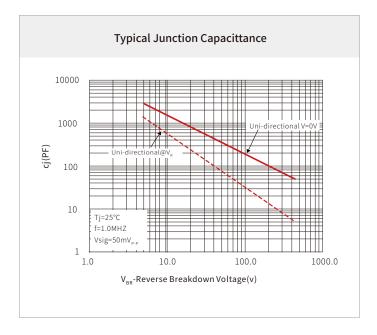






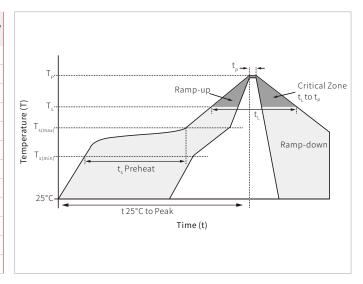






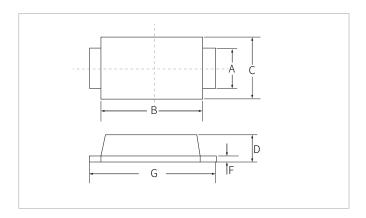
SOLDERING PARAMETERS

	Reflow Condition	Lead-free assembly	
	Temperature Max (T _{s(min)})	150°C	
Pre Heat	Temperature Max $(T_{s(max)})$	200°C	
	Time (min to max) (t_s)	60 – 180 secs	
Average rar	mp up rate (Liquidus Temp (T_L) to peak	3°C/second max	
	$T_{s(max)}$ to T_L - Ramp-up Rate	3°C/second max	
Reflow	Temperature (T」) (Liquidus)	217°C	
Rellow	Time (min to max) (t₁)	60 – 150 seconds	
Peak Ten	nperature (T,)	260°C	
Time with	nin 5°C of actual peak Temperature (t _p)	20 – 40 seconds	
Ramp-do	own Rate	6°C/second max	
Time 25°	C to peak Temperature (T♭)	8 minutes max.	
Do not ex	ceed	260°C	



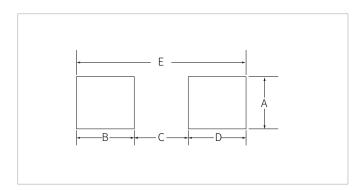


SMAF PACKAGE INFORMATION



Ref.	Millim	neters	Inches		
	Min	Max	Min	Max	
А	1.35	1.60	0.053	0.063	
В	3.40	3.80	0.134	0.145	
С	2.40	2.80	0.094	0.110	
D	0.95	1.45	0.037	0.057	
F	0.15	0.22	0.006	0.009	
G	4.40	4.80	0.173	0.189	

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millin	neters	Inches		
ive.	Min	Max	Min	Max	
А	1.70	-	0.067	-	
В	2.50	-	0.098	-	
С	-	1.5	-	0.059	
D	2.50	-	0.098	-	
Е	6.50REF		0.25	6REF	

ORDERING INFORMATION

Part Number	Package	QTY/Reel	Reel Size
TPSMAF18A	SMAF	5000PCS	13"



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